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Understanding Embedded - DSP (Digital Signal Processors)

Embedded - DSP (Digital Signal Processors) are specialized microprocessors designed to perform complex mathematical computations on digital signals in real-time. Unlike general-purpose processors, DSPs are optimized for high-speed numeric processing tasks, making them ideal for applications that require efficient and precise manipulation of digital data. These processors are fundamental in converting and processing signals in various forms, including audio, video, and communication signals, ensuring that data is accurately interpreted and utilized in embedded systems.

Applications of <u>Embedded - DSP (Digital Signal Processors)</u>

Details		
Product Status	Obsolete	
Туре	SC140 Core	
Interface	Communications Processor Module (CPM)	
Clock Rate	300MHz	
Non-Volatile Memory	External	
On-Chip RAM	512kB	
Voltage - I/O	3.30V	
Voltage - Core	1.60V	
Operating Temperature	-40°C ~ 75°C (TJ)	
Mounting Type	Surface Mount	
Package / Case	332-BFBGA, FCBGA	
Supplier Device Package	332-FCBGA (17x17)	
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/msc8101m1500f	

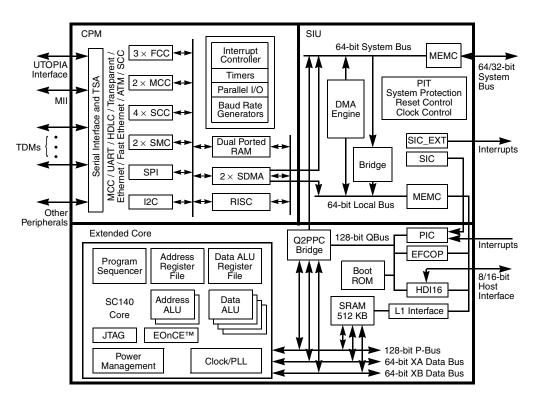
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. . Jescale Semiconductor Product Brief

MSC8101

Networking Digital Signal Processor



The Freescale

MSC8101 16-bit

Digital Signal

Processor is the first

member of the family of

DSPs based on the

StarCore™ SC140 DSP

core.

Figure 1. MSC8101 Block Diagram

The Freescale MSC8101 DSP is a very versatile device that integrates the high-performance SC140 four-ALU (arithmetic logic unit) DSP core along with 512 KB of on-chip memory, a communications processor module (CPM), a 64-bit bus, a very flexible system integration unit (SIU), and a 16-channel DMA controller on a single device. With its four-ALU core, the MSC8101 can execute up to four multiply-accumulate (MAC) operations in a single clock cycle. The MSC8101 CPM is a 32-bit RISC-based communications protocol engine that can network to time-division multiplexed (TDM) highways, Ethernet, and asynchronous transfer mode (ATM) backbones. The MSC8101 60x-compatible bus interface connects to multi-master system architectures. The large on-chip memory, 512 KB, reduces the need for off-chip program and data memories. The MSC8101 offers 1500 DSP MMACS (1200 core and 300 EFCOP) performance using an internal 300 MHz clock with a 1.6 V core and independent 3.3 V input/output (I/O).





Features

- SC140 core
 - Architecture optimized for efficient C/C++ code compilation
 - Four 16-bit ALUs and two 32-bit AGUs
 - 1200 DSP MIPS, 1200 MMACS, 3000 RISC MIPS, running at 300 MHz
 - Very low power dissipation—less than 0.25 W for the core running full speed at 1.6 V
 - Variable-length execution set (VLES) execution model
 - JTAG/enhanced OnCE debug port
- 150 MHz communications processor module (CPM)
 - Programmable protocol machine using a 32-bit RISC engine
 - 155 Mbps ATM interface (including AAL 0/1/2/5)
 - 10/100 Mbit Ethernet interface
 - Up to four E1/T1 interfaces or one E3/T3 interface and one E1/T1 interface
 - HDLC support up to T3 rates, or 256 channels
- 100 MHz 64- or 32-bit wide bus interface
 - Bursts for high efficiency
 - Glueless interface to 60x-compatible bus systems
 - Multi-master support
- Enhanced filter coprocessor (EFCOP)
 - Independently and concurrently executes long filters (such as echo cancellation)
 - Runs at 250/275/300 MHz and provides 250/275/300 MMACS performance
- Programmable memory controller
 - Control for up to eight banks of external memory
 - User-programmable machines (UPM) allowing glueless interface to various memory types (SRAM, DRAM, EPROM, and Flash memory) and other user-definable peripherals
 - Dedicated pipelined SDRAM memory interface
- Large on-chip SRAM
 - 256K 16-bit words (512 KB)
 - Unified program and data space configurable by the application
 - Word and byte addressable
- DMA controller
 - 16 DMA channels, FIFO based, with burst capabilities
 - Sophisticated addressing capabilities
- Small footprint package: 17 mm × 17 mm lidded FC-PBGA package with lead-bearing or lead-free spheres
- Very low power consumption: separate power supply for internal logic (1.6 V) and for I/O (3.3 V)
- Enhanced 16-bit parallel host interface (HDI16) that supports a variety of microcontroller, microprocessor, and DSP bus interfaces
- Phase-lock loops (PLLs)
 - System PLL
 - CPM DPLLs (SCC and SCM)
- Process technology: 0.13 micron copper interconnect



Target Applications

The MSC8101 targets applications requiring very high performance, very large amounts of on-chip memory, and such networking capabilities as:

- Third-generation wideband wireless infrastructure systems
- Packet telephony systems
- Multi-channel modem banks
- Multi-channel xDSL

Product Documentation

The documents listed in **Table 1** are required for a complete description of the MSC8101 and are necessary to design properly with the part. Documentation is available from the following sources (see back cover for details):

- A local Freescale distributor
- A Freescale Semiconductor sales office
- A Freescale Literature Distribution Center
- The World Wide Web (WWW)

Table 1. MSC8101 Documentation

Name	Description	Order Number
MSC8101 Technical Data	MSC8101 features list and physical, electrical, timing, and package specifications	MSC8101/D
MSC8101 User's Guide	Detailed functional description of the MSC8101 memory configuration, operation, and register programming	MSC8101UG/D
MSC8101 Pocket Guide	Quick reference information for application development.	MSC8101PG/D
MSC8101 Reference Manual	Detailed description of the MSC8101 processor core and instruction set	MSC8101RM/D
SC140 DSP Core Reference Manual	Detailed description of the SC140 family processor core and instruction set	MNSC140CORE/D
Application Notes	Documents describing specific applications or optimized device operation including code examples	See the MSC8101 product website



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